

**REPLY UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2800**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: Angyal *et al.* **Conf. No.:** 4705
Serial No.: 10/710,706 **Art Unit:** 2813
Filed: 07/29/2004 **Docket No.:** FIS920040028US1 (IBMF-0053)
Examiner: Monica D. Harrison

Title: INTERLEVEL DIELECTRIC
LAYER AND METAL LAYER
SEALING

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

*not entered
monica D. Harrison
6/23/06*

AFTER FINAL REQUEST FOR RECONSIDERATION

Sir:

INTRODUCTORY COMMENTS

In response to the Final Office Action of February 22, 2006, please re-consider the rejections based on the following remarks.